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DERWENT-ACC-NO: 1996-172710
DERWENT-WEEK: 199844
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TITLE: Connecting electronic component to substrate with several contact faces - which contain contact humps of gold, at least to considerable extent

INVENTOR: ELDRING, J

PATENT-ASSIGNEE:

ASSIGNEE

CODE

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FRAU

PRIORITY-DATA: 1994DE-4434104 (September 23, 1994)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
KR 97706606 A	November 3, 1997		000	H01L023/485
<u>DE 19535282 A1</u>	March 28, 1996		013	H01L021/603
WO 9609647 A1	March 28, 1996	G	029	H01L023/485
JP 10503059 W	March 17, 1998		030	H01L023/12

DESIGNATED-STATES: CA JP KR US AT BE CH DE DK ES FR GB GR IE IT LU MC NL PT SE

CITED-DOCUMENTS:DE 2348325; EP 388011 ; EP 402756

APPLICATION-DATA:

PUB-NO	APPL-DATE	APPL-NO	DESCRIPTOR
KR97706606A	September 22, 1995	1995WO-DE01322	
KR97706606A	March 14, 1997	1997KR-0701665	
KR97706606A		WO 9609647	Based on
DE19535282A1	September 22, 1995	1995DE-1035282	
WO 9609647A1	September 22, 1995	1995WO-DE01322	
JP10503059W	September 22, 1995	1995WO-DE01322	
JP10503059W	September 22, 1995	1996JP-0510532	
JP10503059W		WO 9609647	Based on

INT-CL (IPC): H01 L 21/60; H01 L 21/603; H01 L 23/12; H01 L 23/485; H05 K 3/32

ABSTRACTED-PUB-NO: DE19535282A

BASIC-ABSTRACT:

One component surface locates Al contacting faces for contact faces on the substrate via contacting metallising on both faces, consisting mostly of Au. The substrate contact faces contain contact humps, mostly of Au. The component Al contact faces are aligned with the substrate ones.

Then, under pressure and temp. effect, the two types of contact faces are firmly coupled. Pref. the substrate contact face humps are so formed that they contain a

narrow peak and a wider base. The humps may be formed on the substrate contact faces by a mechanical process, such as ball-bumping, contg. 95 wt. % of Au and 5 % of Td.

USE/ADVANTAGE - For integrated circuits and multi-chip techniques, with reduced mechanical and thermal stress of the electronic components.

CHOSEN-DRAWING: Dwg.1/4

TITLE-TERMS: CONNECT ELECTRONIC COMPONENT SUBSTRATE CONTACT FACE CONTAIN CONTACT HUMP
GOLD EXTENT

DERWENT-CLASS: U11 V04

EPI-CODES: U11-D03B1; U11-D03B3; V04-R04;

SECONDARY-ACC-NO:

Non-CPI Secondary Accession Numbers: N1996-145095